

# AP55T06GI-HF-VB Datasheet

# N-Channel 60-V (D-S) MOSFET

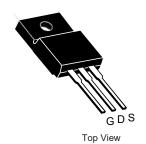
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>		
60	0.010 at V <sub>GS</sub> = 10 V	70		
00	0.012 at V <sub>GS</sub> = 4.5 V	55		

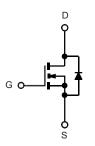
## **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25	°C, unless other	wise noted)			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Dusin Compant /T = 475 °C\b	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	70		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	] 'D	50ª		
Pulsed Drain Current		I <sub>DM</sub>	200	A	
Continuous Source Current (Diode Conduction)		Is	50ª		
Avalanche Current		I <sub>AS</sub>	50	1	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ	
Maximum Power Discination	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>	] vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Marian and Long-Marian As Analysis and	t ≤ 10 sec	R <sub>thJA</sub>	15	18	°C/W		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		40	50			
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1			

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t \le 10 \text{ s}$ .



Parameter	Symbol	Test Conditions	Min.	Typ.a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu A$	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	
	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			Α
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.010		
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.016		0
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.020		μA
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.012		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S
Dynamic						
Input Capacitance	C <sub>iss</sub>			2650		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		470		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			225		
Total Gate Charge <sup>c</sup>	Qg			47	70	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12		
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 0.6 $\Omega$ $I_D \cong 50$ A, $V_{GEN}$ = 10 V, $R_g$ = 2.5 $\Omega$		15	25	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			35	50	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30	
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)			·	
Pulsed Current	I <sub>SM</sub>				70	Α
Diode Forward Voltage	V <sub>SD</sub>	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		45	100	ns

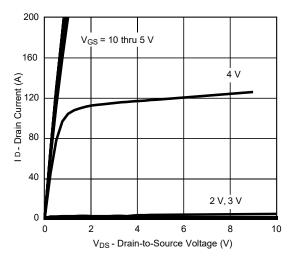
### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2~\%$ .
- c. Independent of operating temperature.

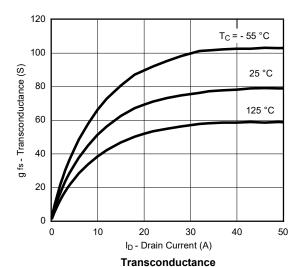
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



# TYPICAL CHARACTERISTICS (25 °C unless noted)



#### **Output Characteristics**



C - Capacitance (pF) 2500 2000 1500 1000  $\mathsf{C}_{\mathsf{oss}}$ 500

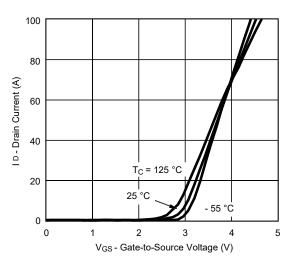
20

 $\overline{C_{iss}}$ 

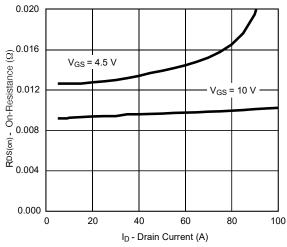
V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

30

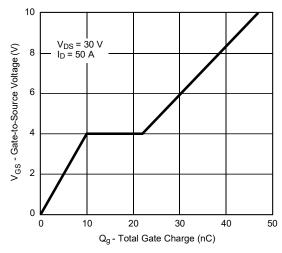
60



#### **Transfer Characteristics**



On-Resistance vs. Drain Current



**Gate Charge** 

 $C_{\rm rss}$ 

10

0

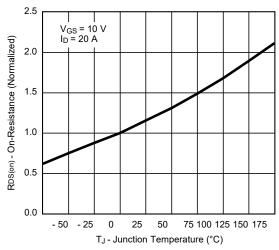
0

4000 3500

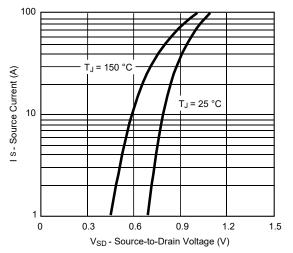
3000



# TYPICAL CHARACTERISTICS (25 °C unless noted)



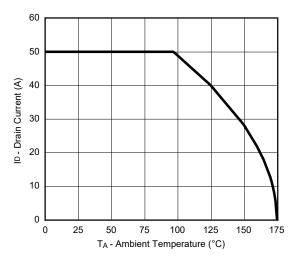
On-Resistance vs. Junction Temperature

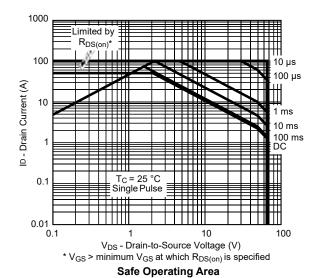


Source-Drain Diode Forward Voltage

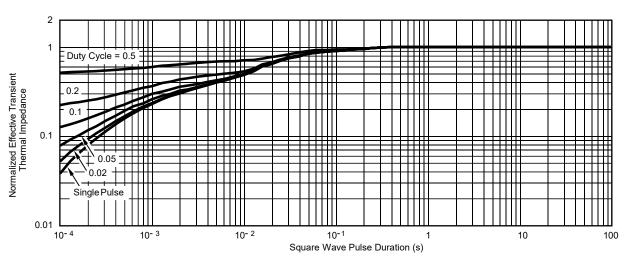


### THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



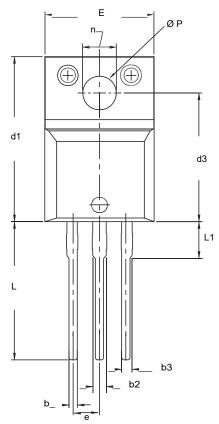
Normalized Thermal Transient Impedance, Junction-to-Case

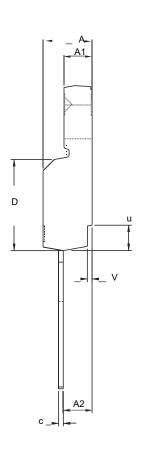
服务热线:400-655-8788

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# **TO-220 FULLPAK (HIGH VOLTAGE)**





DIM.	MILLIN	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100	BSC	
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

## DWG: 5972

## Notes

- To be used only for process drawing.
  These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
  All critical dimensions should C meet C<sub>pk</sub> > 1.33.
  All dimensions include burrs and plating thickness.
  No chipping or package damage.



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